



- NOTES:
- PLATING THICKNESS
Ni: 1.27~8.89 MICRON.
Au: 0.30 MICRON MIN.
(EXCEPT 0.30~1.00 MICRON AT SOLDER PADS.)
 - CONNECTION.
(A-C), (B-D), (B-2-S/R), (F-3), (G-J-4), (H-1)
 - CAMBER : 50.00 MICRON MAX.
 - METALLIZATION RUNDOWN 0.20 MAX.
 - EXPOSURE OF CERAMIC SURFACE AND METALLIZED PATTERN OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
 - PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
 - STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
 - SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

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TOLERANCE X ±1% XXX N.L.T.±0.13 ANGLES	REVISION				SBB ATTACHED EXCEPTIONS SHEET.		TITLE	
	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.		5X7 OSC PKG	
	12 : 1	mm	3rd				PART NO.	REV.
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	S5070CLK1		0
90%MIN.A1203 (NA-311B BLACK)	Shigetomi	Koike	Ohba	Kumura	Sakima	M03111-39		SHT/OF 1/8